SERCON410B

DATASHEET

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2. A critical component is any component of a life support device or system whose failure to perform can reasonably be expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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NOTES:

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SERCON410B

SERCOS INTERFACE CONTROLLER

PRELIMINARY DATA

- Single-chip controller for SERCOS interface
- Real time communication for industrial control systems
- 8/16-bit bus interface, Intel and Motorola control signals
- Dual port RAM with 1024 words * 16-bit
- Data communications via optical fiber rings, RS 485 rings and RS 485 busses
- Maximum transmission rate of 4 Mbaud with internal clock recovery
- Maximum transmission rate of 10 Mbaud with external clock recovery
- Internal repeater for ring connections
- Full duplex operation
- Modulation of power of optical transmitter diode
- Automatic transmission of synchronous and data telegrams in the communication cycle
- Flexible RAM configuration, communication data stored in RAM (single or double buffer) or transfer via DMA
- Synchronization by external signal
- Timing control signals
- Automatic service channel transmission
- 100-pin plastic flat-pack casing

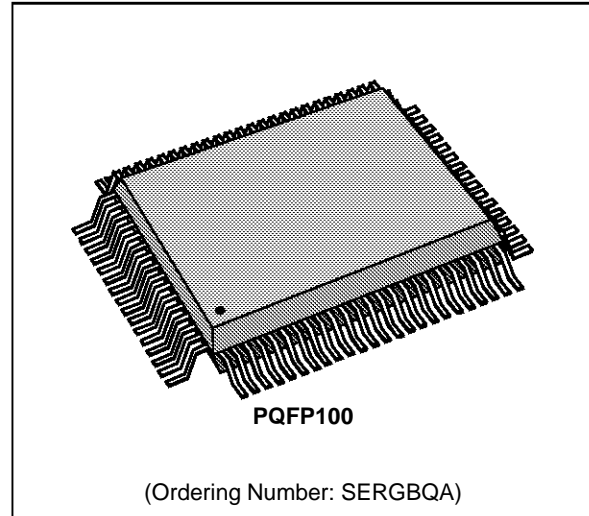**PQFP100**

(Ordering Number: SERGBQA)

May 1994

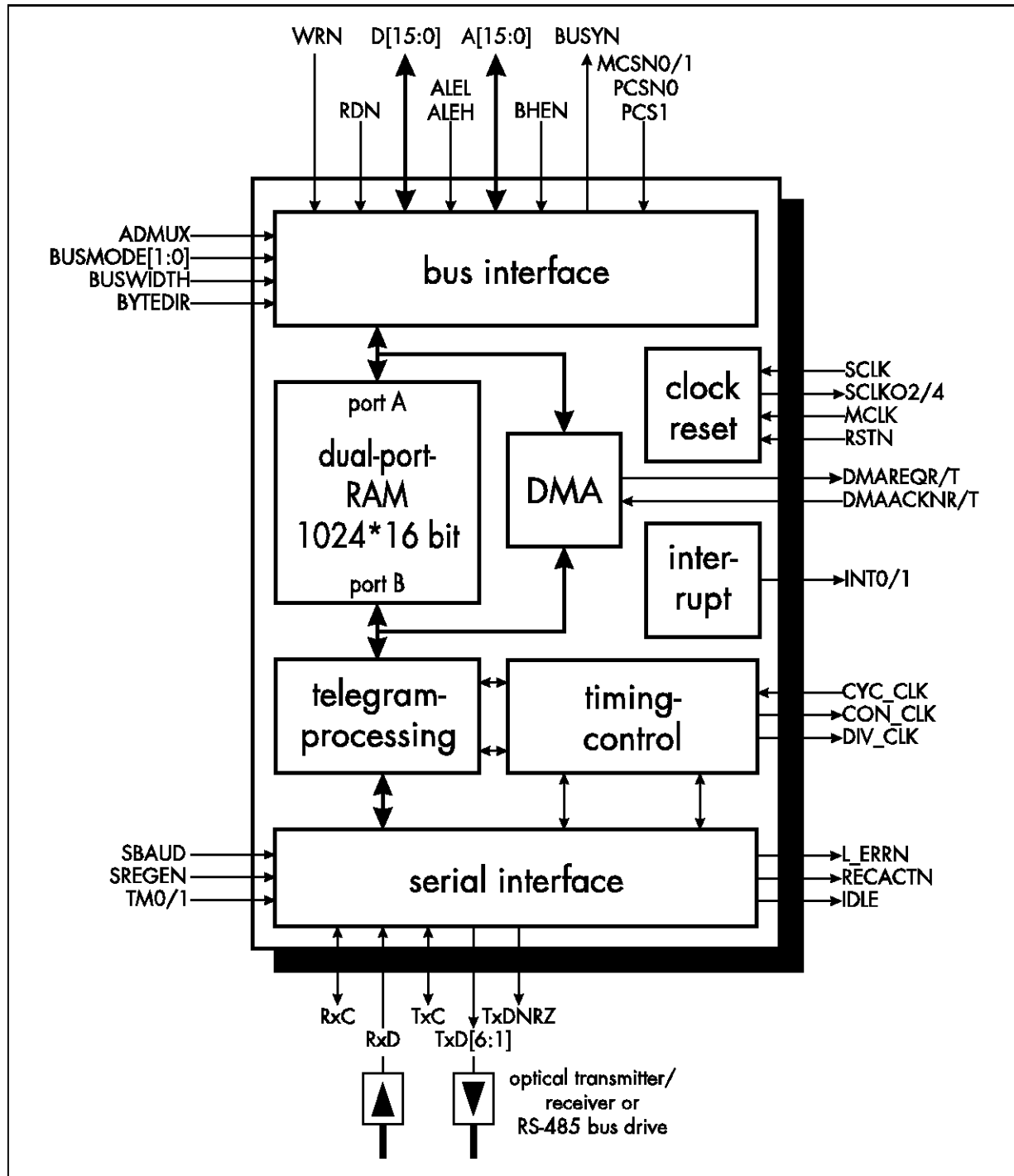**Figure 1. SERCON410B Block Diagram**

Figure 2. SERCON410B Pin Configuration
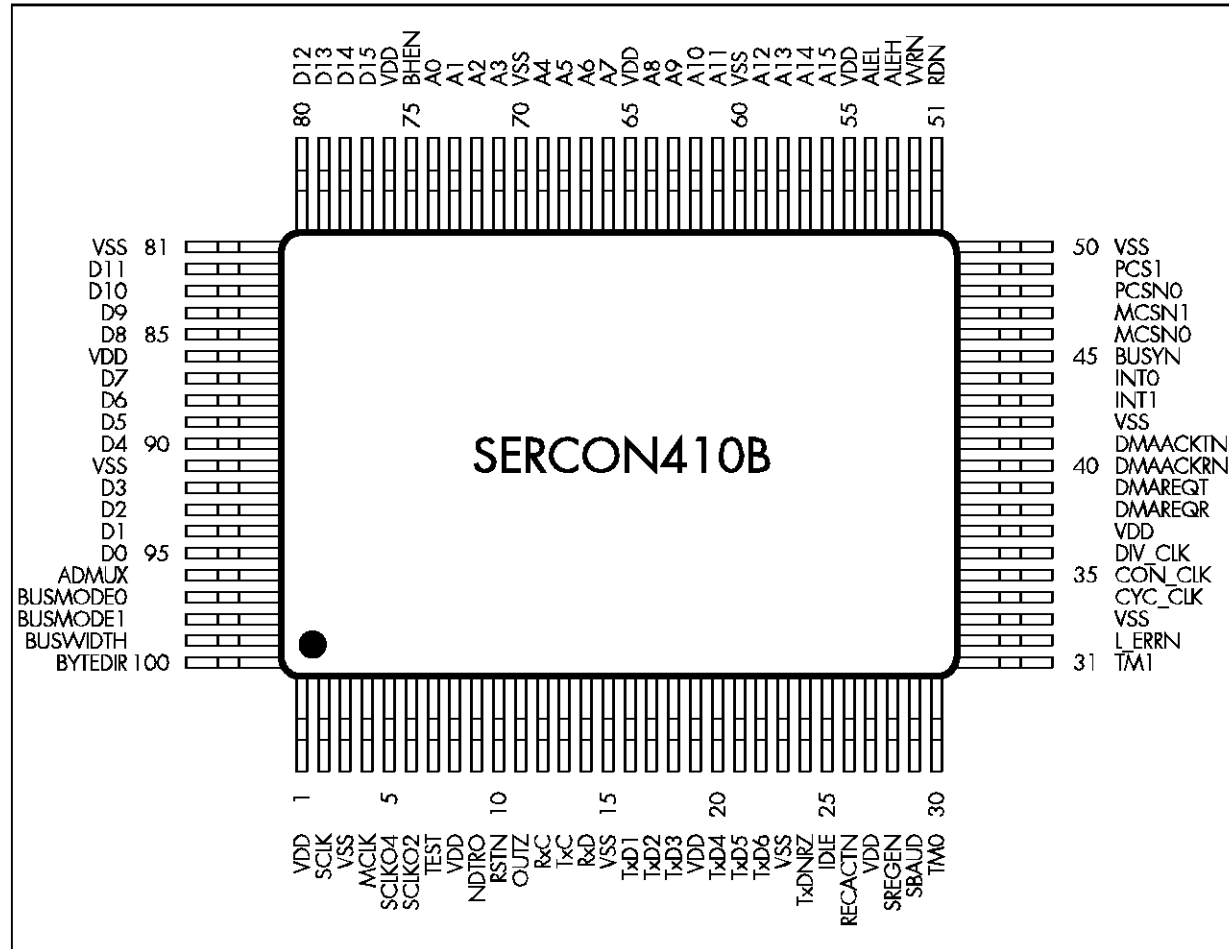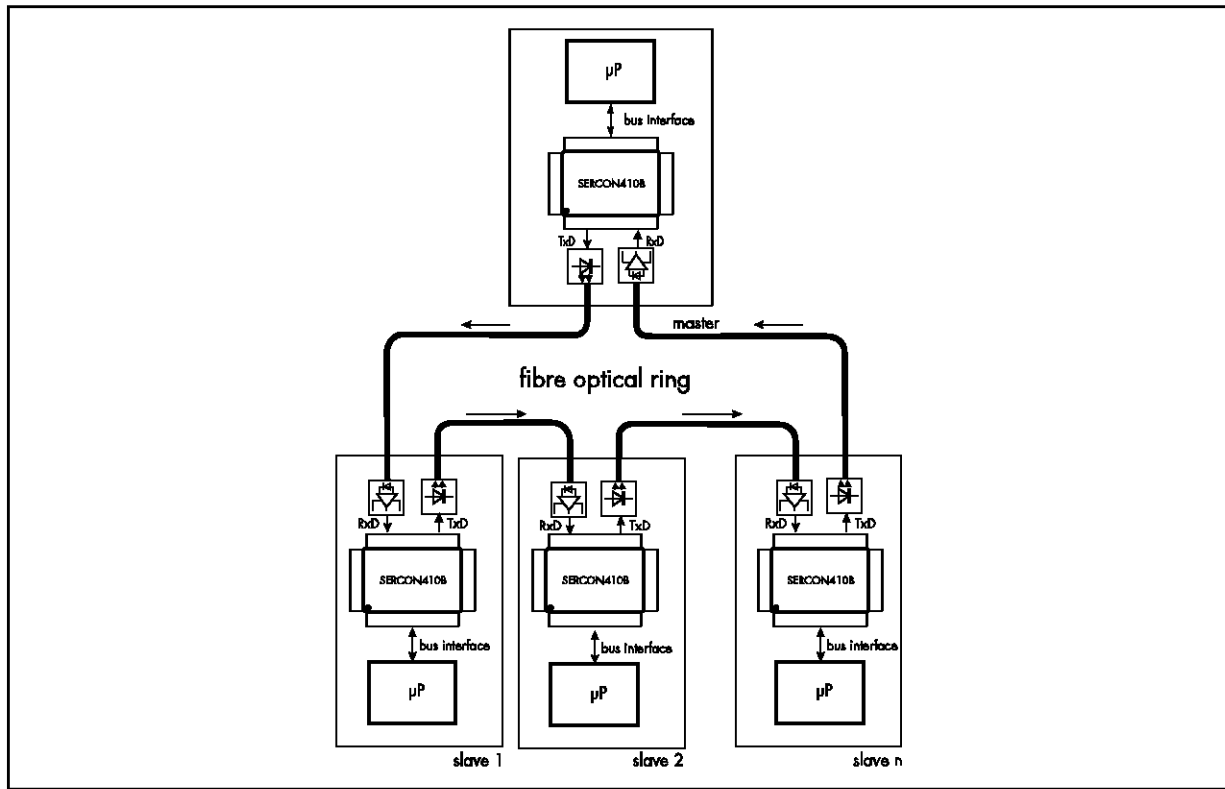
Figure 3. SERCOS Interface with Ring Connection

Figure 4. SERCON410B with RS-485 bus Connection

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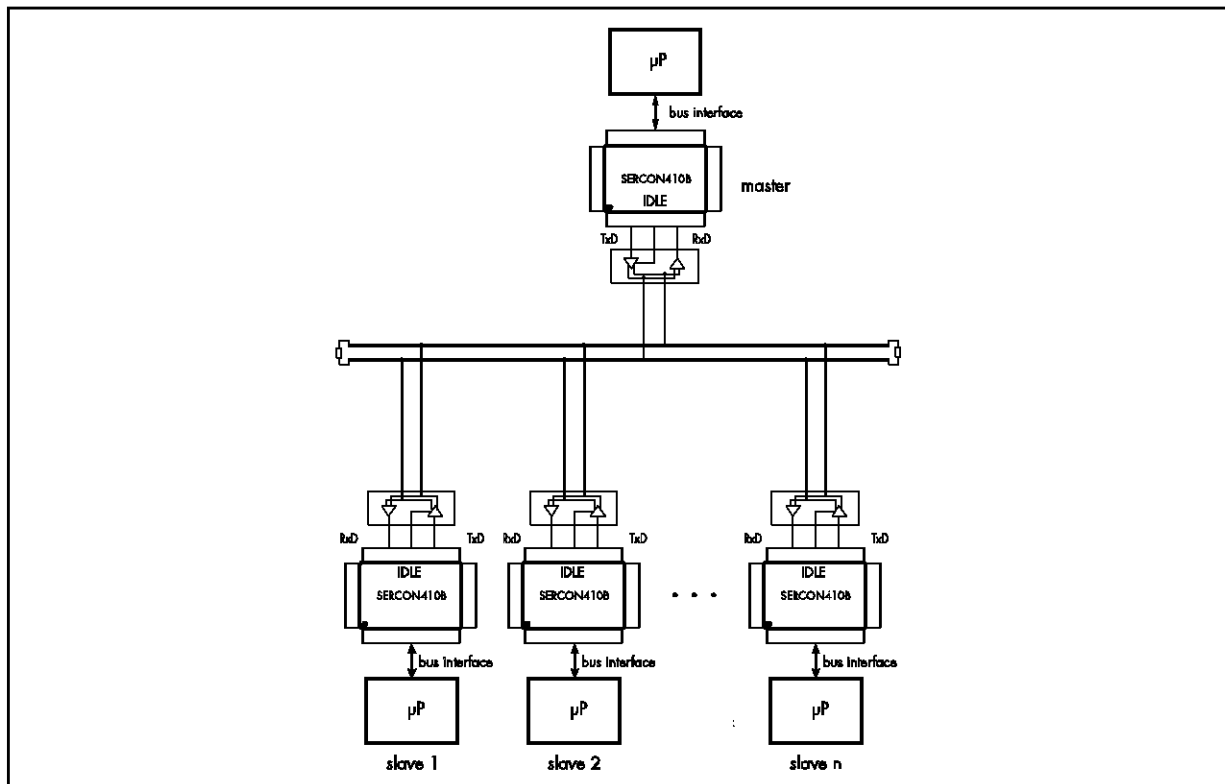
1 GENERAL DESCRIPTION

The SERCOS interface controller SERCON410B is an integrated circuit for SERCOS interface communication systems. The SERCOS interface is a digital interface for communication between systems which have to exchange information cyclically at short, fixed intervals (65 μs to 65 ms). It is appropriate for the synchronous operation of distributed control or test equipment (e.g. connection between drives and numeric control).

A SERCOS interface communication system consists of one master and several slaves (Fig. 3). These units are connected by a fiber optical ring. This ring starts and ends at the master. The slaves regenerate and repeat their received data or send their own telegrams. By this method the telegrams sent by the master are received by all slaves while the master receives data telegrams from the slaves. The optical fiber assures a reliable high-speed data transmission with excellent noise immunity.

The SERCOS interface controller contains all the hardware-related functions of the SERCOS interface and considerably reduces the hardware

costs and the computing time requirements of the microprocessor. It is the direct link between the electro-optical receiver and transmitter and the microprocessor that executes the control algorithms. The SERCON410B can be used both for SERCOS interface masters and slaves.

The circuit contains the following functions (Fig. 1):

- Interface to the microprocessor with a data bus width of 8 or 16 bits and with control lines according to Intel or Motorola standards.

- A serial interface for making a direct connection with the optical receiver and transmitter of the fiber optic ring or with drivers to an electric ring or bus. Data and clock regeneration, the repeater for ring topologies and the serial transmitter and receiver are integrated. The signals are monitored and test signals generated. The serial interface operates up to 4Mbaud without external circuitry and up to 10 Mbaud with external clock regeneration.

- A dual port RAM (1024 * 16 bit) for control and communication data. The organization of the memory is flexible.

- Telegram processing for automatic transmission and monitoring of synchronous and data telegrams. Only transmission data which is intended for the particular interface user is processed. The transmitted data is either stored in the internal RAM (single or double buffer) or transferred via direct memory access (DMA). The transmission of service channel information over several communication cycles is executed automatically.

In addition to the SERCOS interface the SERCON410B can also be used for other real-time communications tasks. As an alternative to the fiberoptical ring also bus topologies with RS-485 signals are supported (Fig. 4). The SERCON410B is therefore suitable for a wide range of applications.

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2 PIN DESCRIPTION

Table 1. SERCON410B I/O Port Function Summary

Signal (s)	Pin (s)	IO	Function
D15-0	77-80, 82-85, 87-90, 92-95	I/O	Data bus: for 8-bit-wide bus interfaces, data is written to and read via D7-0, for 16-bit-wide bus interfaces via D15-0. When ADMUX is 1, the address which is stored in the address latch with ALEL and ALEH is input via D15-0.
A15-0	56-59, 61-64, 66-69, 71-74	I/O	Address bus: when ADMUX is 0 the pins are inputs, when ADMUX is 1, they are outputs for the address stored with ALEL (A7-0) and ALEH (A15-8). In the 8-bit bus mode, A0 distinguishes which byte is transmitted via D7-0 (depends on BYTEDIR). In the 16-bit bus mode, data is tansferred via D7-0 only when A0 is 0. A10-1 selects the words of the internal RAM; A6-1the control registers.
ALEL, ALEH	54, 53	I	Address latch enable, low and high, active high: they are only used when ADMUX is 1. When ALEL/ALEH is 1, the signals go from the data bus to the address bus, when ALEL/ALEH = 0, they store the address. When ADMUX is 0, ALEL/ALEH have to be connected to V_{DD}.
RDN	51	I	Read: for the Intel bus interface, data is read when RDN is 0. For the Motorola bus interface, data is read or written to when RDN is 0 (BUSMODE1 = 0) or RDN is 1 (BUSMODE1 = 1).
WRN	52	I	Write: for the Intel bus interface, data is written to when WRN is 0. For the Motorola bus interface, WRN selects read (WRN = 1) and write (WRN = 0) operations of the data bus.
BHEN	75	I	Byte high enable, active low: in the 16-bit bus mode, data is transferred via D15-8 when BHEN is 0.
MCSN0, MCSN1	46,47	I	Memory chip select, active low: to access the internal RAM MCSN0 and MCSN1 must be 0.
PCSN0, PCS1	48,49	I	Periphery chip select, active low (PCSN0) and active high (PCSN1): to access the control registers PCSN0 must equal 0 and PCS1 must equal 1.
BUSYN	45	O	RAM busy, active low: becomes active if an access to an address of the dual port RAM is performed simultaneously to an access to the same memory location by the internal telegram processing.
DMAREQR	38	O	DMA request receive, active high: becomes active if data from the receive FIFO can be read. At the beginning of the read operation of the last word of the receive FIFO, DMAREQR becomes inactive.
DMAACKRN	40	I	DMA acknowledge receive, active low: when DMAACKRN is 0, the receive FIFO is read, independent of the levels on A6-1 and the chip select signals.
DMAREQT	39	O	DMA request transmit, active high: becomes active when data can be written to the transmit FIFO. DMAREQT becomes inactive again at the beginning of the last write access to the transmit FIFO.
DMAREQTN	41	I	DMA acknowledge transmit, active low: when DMAACKTN is 0, the transmit FIFO is written to when there is a bus write access independent of the levels on A6-1 and the chip select signals.
ADMUX	96	I	Address data bus: when ADMUX is 0 A15-0 are the address inputs, when ADMUX is 1 A15-0 are the outputs of the address latch.
BUSMODE0, BUSMODE1	97,98	I	Bus mode: BUSMODE0 = 0 turns on the Intel bus interface (RDN = read, WRN = write), BUSMODE0 = 1 selects the Motorola interface (RDN = data strobe, WRN = read/write). BUSMODE1 selects the 0-active data strobe (BUSMODE1 = 0) or the 1-active data strobe (BUSMODE1 = 1).
BUSWIDTH	99	I	Bus width: selects the 8-bit- (0) or the 16-bit-wide interface (1).

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PIN DESCRIPTION (Continued)

Table 1. SERCON410B I/O Port Function Summary (Continued)

Signal (s)	Pin (s)	IO	Function
BYTEDIR	100	I	Byte address sequence: when BYTEDIR is 0, A0 = 0 addresses the lower 8 bits of a word (low byte first), when BYTEDIR is 1, the upper 8 bits of a word are addressed (high byte first).
INT0, INT1	44,43	O	Interrupts, active low or active high. Interrupt sources and signal polarity are programmable.
SREGEN	28	I	Internal regeneration. When SREGEN is 0, clock and data regeneration are turned off. RxC and TxC are clock inputs. When SREGEN is 1, clock and data regeneration are turned on. RxC and TxC output the internally generated clocks.
SBAUD	29	I	Baud rate. When regeneration is turned on, SBAUD selects the baud rate (f_{SCLK}/16 when SBAUD is 0, f_{SCLK}/32 when SBAUD is 1). Can be overwritten by the microprocessor.
RxD	14	I	Receive data for the serial interface.
RxC	12	I/O	Receive clock for the serial interface. When regeneration is turned off (SREGEN = 0), clock input for the serial receiver and transmitter (only when repeater is turned on); when regeneration is turned on (SREGEN = 1) output of the internally generated receive clock. The maximum frequency is 10 MHz.
RECACTN	26	O	Receive active, active low. Indicates that the serial receiver is receiving a telegram.
TxD1	16	O	Transmit data. The pin can be switched to a high impedance state.
TxD6-2	22,21,20, 18,17	O	Transmit data or output port. The pins either output the serial data or can be used as parallel output ports. When they output transmit data, each pin can be switched to a high impedance state individually.
TxDNRZ	24	O	NRZ-coded transmit data.
TxC	13	I/O	Transmit clock for the serial interface. When regeneration is turned off (SREGEN = 0) and the repeater is turned off, it is the clock input for the serial transmitter; when regeneration is turned on (SREGEN = 1) it is the output for the internally generated transmit clock. The maximum frequency is 10 MHz.
IDLE	25	O	Transmitter active, active low. When transmitting own data IDLE is 0.
TM0, TM1	30,31	I	Turn on test generator: TM0 = 0 switches TxD1-6 to continuous signal light, TM1 = 0 switch-over to zero bit stream. The processor can overwrite the level of TM1-0.
L_ERRN	32	O	Line error, active low: goes low when signal distortion is too high or when the receive signal is missing. The operating mode is programmed by the processor.
CYC_CLK	34	I	SERCOS interface cycle clock: CYC_CLK synchronizes the communication cycles. The polarity is programmable.
CON_CLK	35	O	Control clock: becomes active within a communication cycle. Time, polarity and width are programmable.
DIV_CLK	36	O	Divided control clock: becomes active several times within a ommunication cycle. Number of pulses, start time, repetition rate and polarity are programmable, the pulse width is 1μs.
SCLK	2	I	Serial clock for clock regeneration: the frequency is 16 or 32 times the baud rate, the maximum frequency is 64 MHz.

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PIN DESCRIPTION (Continued)

Table 1. SERCON410B I/O Port Function Summary (Continued)

Signal (s)	Pin (s)	IO	Function
SCLKO2	6	O	Clock output: outputs the SCLK clock divided by 2.
SCLKO4	5	O	Clock output: outputs the SCLK clock divided by 4.
MCLK	4	I	Master clock for telegram processing and timing control, frequency 12 to 20 MHz.
RSTN	10	I	Reset, active low. Must be zero for at least 50 ns after power on.
TEST	7	I	Test, active high. Has to be tied to V_{SS}.
OUTZ	11	I	Puts outputs into high impedance state, active high: OUTZ is 1 puts all pins into a high impedance state. The clocks are turned off and the circuit is reset. For the in-circuit test and for turning on the powerdown mode.
NDTRO	9	O	NAND tree output. For the test at the semiconductor manufacturers and for the connection test after board production. NDTRO is not set to a high impedance state.
V_{SS}	3,15,23, 33,42, 50,60, 70,81, 91		Ground pins.
V_{DD}	1,8,19, 27,37, 55,65, 76,86		Power supply +5 V $\pm$ 5%.

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3 ELECTRICAL CHARACTERISTICS

3.1 ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{DD}	Supply Voltage	-0.3 to 7.0	V
V_I	Input Voltage	V_{SS} - 0.3 to V_{DD} + 0.3	V
V_O	Output Voltage	V_{SS} - 0.3 to V_{DD} + 0.3	V
T_{STG}	Storage Temperature	-55 to +150	°C

3.2 RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Value		Unit
		Min.	Max.	
T_A	Operating Temperature	-40	85	°C
V_{DD}	Operating Supply Voltage	4.75	5.25	V
f_{SCLK}	Clock Frequency SCLK		64	MHz
f_{MCLK}	Clock Frequency MCLK		20	MHz
f_{TxC}, f_{RxC}	Clock Frequency TxC, RxC		10	MHz

3.3 DC ELECTRICAL CHARACTERISTICS

(V_{DD} = 5V $\pm$ 5% TA = -40°C to +85°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
V_{IL}	Input Low Level Voltage				0.8	V
V_{IH}	Input High Level Voltage		2.4			V
V_{T+}	Schmitt trig. +ve threshold	All pins except D15-0, A15-0, ALEL, ALEH, RDN, WRN, BHEN, MCSN0-1, PCSN0, PCS1, DMAACKTN, DMAACKRN		2.0	2.4	V
VT-	Schmitt trig. +ve threshold		0.6	0.8		V

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DC ELECTRICAL CHARACTERISTICS (Continued)

Symbol	Parameter	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
I_{IL}	Low Level Input Current (Pull-up resistor)	$VI = V_{SS}$	-450	-50	-30	µA
I_{IH}	High Level Input Current	$VI = V_{DD}$	-10	<1	10	µA
V_{OL}	Low level Output Voltage, all O- and I/O-pins except TXD6-1	$I_{OI} = -4$ mA			0.4	V
V_{OH}	High level output voltage, all O- and I/O-pins except TXD6-1	$I_{OH} = +4$ mA	2.4			V
V_{OL}	High level output voltage, all O- and I/O-pins except TXD6-1	$I_{OI} = -8$ mA			0.4	V
V_{OH}	High level output voltage, pins TXD6-1	$IOH = +8$ mA	$V_{DD} - 0.5$			
I_{OZ}	Tri-state output leakage	$V_O = 0$ V or V_{DD}	-10	<1	+10	µA
I_{KLU}	I/O latch-up current	$V<V_{SS}$ $V>V_{DD}$	200mA			mA
V_{ESD}	Electrostatic protection	C=100 pF, R = 1.5 k	2000			V
C_{PIN}	Pin capacitance			10		pF

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3.4 AC ELECTRICAL CHARACTERISTICS

Figure 5. Timing of Clock MCLK and Related Outputs

(C_{load} = 50 pF, V_{DD} = 5 V $\pm$ 5% T_A = -40 °C to +85 °C)
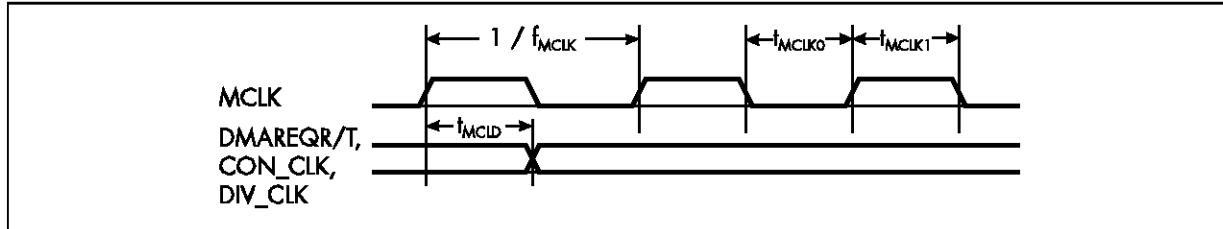
3.4.1 Clock Input MCLK

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
f_{MCLK}	Clock Frequency MCLK	12		20	MHz
t_{MCLK0}	MCLK Low	20			ns
t_{MCLK1}	MCLK High	20			ns
t_{MCLD}	Output Delay Rising Edge MCLK to DMAREQR/T, CON_CLK, DIV_CLK			30	ns

Figure 6. Timing of Clock SCLK
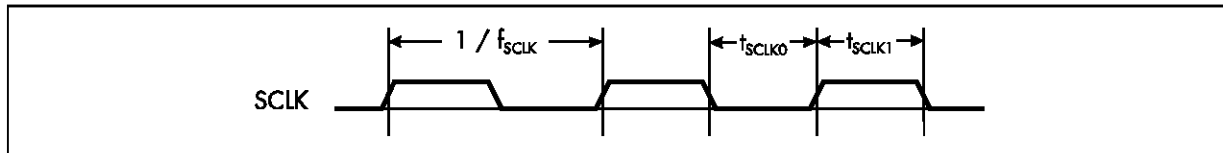
3.4.2 Clock Input SCLK

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
f_{SCLK}	Clock Frequency SCLK			64	MHz
t_{SCLK0}	SCLK Low	6.5			ns
t_{SCLK1}	SCLK High	6.5			ns

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AC ELECTRICAL CHARACTERISTICS (Continued)

Figure 7. Timing of Serial Clock Inputs RxC and TxC and Related Signals
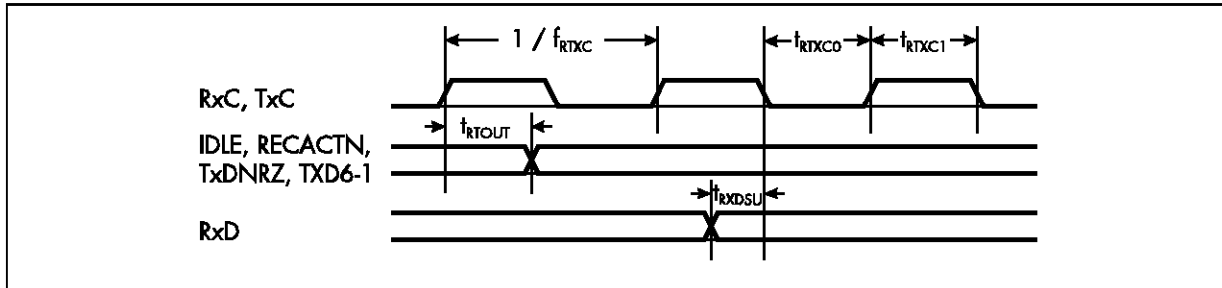
3.4.3 Serial Clock

(SREGEN = 0, external clock regeneration, RxC and TxC are inputs)

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
f_{RTXC}	Clock Frequency RxC, TxC			10	MHz
t_{RTXC0}	RxC, TxC Low	40			ns
t_{RTXX1}	RxC, TxC High	40			ns
t_{RTOUT}	Output Delay RxC, TxC to TxD6-1, TxDNRZ, IDLE, RECACTN			45	ns
t_{RXDSU}	Setup RxD to Falling Edge of RxC	15			ns

Figure 8. Timing of Serial Clock Inputs RxC and TxC and Related Signals
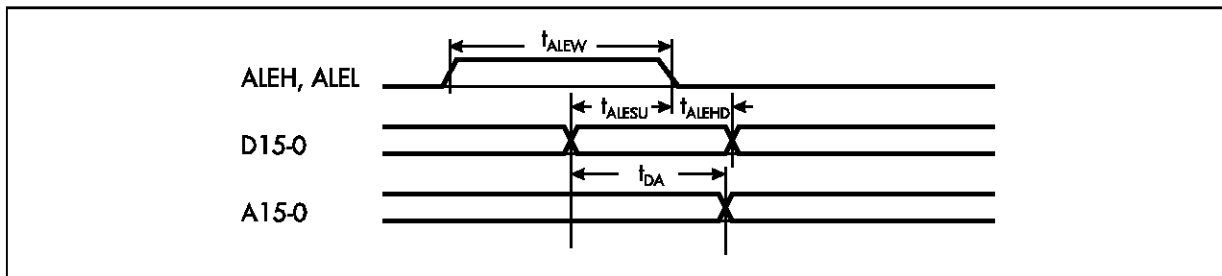
3.4.4 Address Latch

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
t_{ALEW}	Pulse Width ALEL, ALEH	25			ns
t_{ALESU}	Setup Time D15-0 To Falling Edge ALEH, ALEL	10			ns
t_{ALEHD}	Hold Time Falling Edge ALEH, ALEL to D15-0	5			ns
t_{DA}	Delay from D15-0 to A15-0			20	ns

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AC ELECTRICAL CHARACTERISTICS (Continued)

Figure 9. Read Access of Control Registers

3.4.5 Read Access of Control Registers

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
t_{ASU}	Setup time A6-0, BHEN, PCSN0, PCS1, DMAACKNR, WRN (only Motorola mode) to falling edge RDN (Intel or Motorola mode with low active strobe) or rising edge RDN (Motorola mode with high active strobe)	0			ns
t_{AHD}	Hold time A10-0, BHEN, MCSN0-1, WRN (only Motorola mode) to rising edge RDN (Intel Motorola mode with low active strobe) or falling edge RDN (Motorola mode with high active strobe)	0			ns
t_{PAD}	Access time A6-0, BHEN, PCSN0, PCS1, DMAACKNR, WRN (only Motorola mode) to D15-0 valid			50	ns
t_{PRDD}	Access time RDN to D15-0 valid			40	ns
t_{RDZ}	Delay RDN to D15-0 high-Z			15	ns
t_{PRQ}	Delay RDN to DMAREQR low			30	ns

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AC ELECTRICAL CHARACTERISTICS (Continued)

Figure 10. Read Access of Dual Port RAM
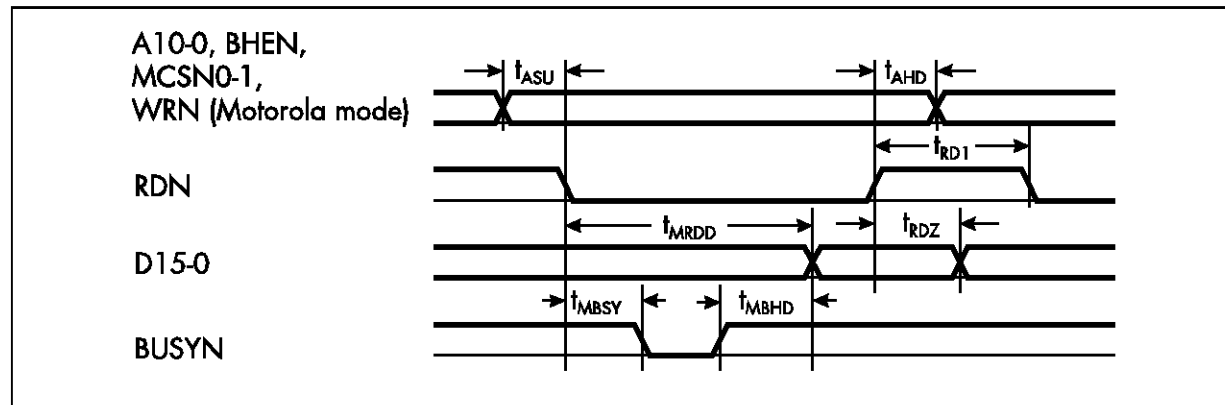
3.4.6 Read Access of Dual Port RAM

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
t_{ASU}	Setup time A10-0, BHEN, MCSN0-1, WRN (only Motorola mode) to falling edge RDN (Intel or Motorola mode with low active strobe) or rising edge RDN (Motorola mode with high active strobe)	0			ns
t_{AHD}	Hold time A10-0, BHEN, MCSN0-1, WRN (only Motorola mode) to rising edge RDN (Intel Motorola mode with low active strobe) or falling edge RDN (Motorola mode with high active strobe)	0			ns
t_{MRDD}	Access time RDN to D15-0 valid			60	ns
t_{MBSY}	Delay RDN to BUSYN low			35	ns
t_{MBHD}	Delay BUSYN high to D15-0 valid			30	ns
t_{RDZ}	Delay RDN to D15-0 high-Z			15	ns
t_{RD1}	RDN and WRN high after end of read access	30			ns

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AC ELECTRICAL CHARACTERISTICS (Continued)

Figure 11. Write Access to Control Registers

3.4.7 Write Access to Control Registers

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
t_{ASU}	Setup time A6-0, BHEN, PCSN0, PCS1, DMAACKNT, WRN (only Motorola mode) to falling edge WRN (Intel mode) or RDN (Motorola mode, strobe active low) or rising edge RDN (Motorola mode, strobe active high)	0			ns
t_{AHD}	Hold time A6-0, BHEN, PCSN0, PCS1, DMAACKNT, WRN (only Motorola mode) to rising edge WRN (Intel mode) or RDN (Motorola mode, strobeactive low) or falling edge RDN (Motorola mode, strobe active high)	0			ns
t_{PWRW}	Pulse width WRN (Intel mode) or RDN (Motorola mode)	30			ns
t_{DSU}	Setup time D15-0 to end of write access	10			ns
t_{DHD}	Hold time D15-0 to end of write access	10			ns
t_{PRQ}	Delay WRN or RDN to DMAREQT low			30	ns

AC ELECTRICAL CHARACTERISTICS (Continued)

Figure 12. Write Access to DUAL Port RAM
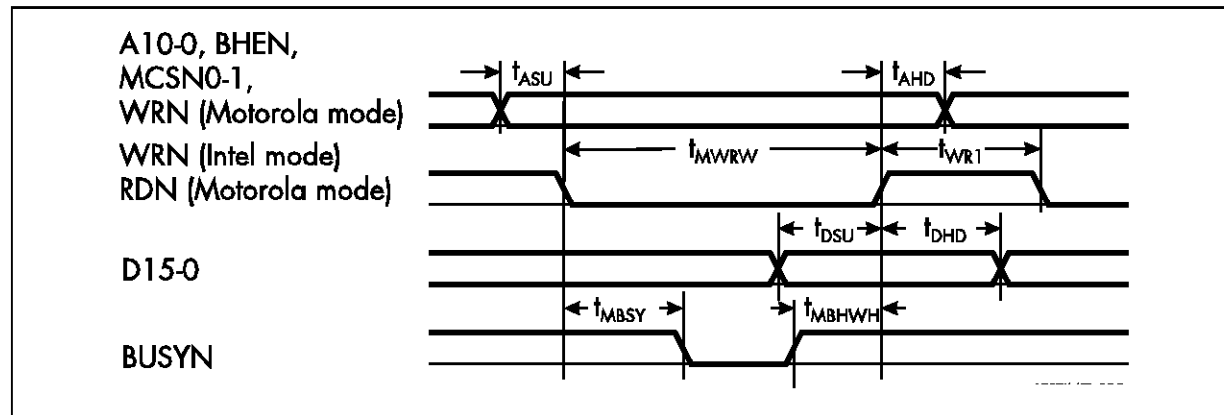
3.4.8 Write Access to Dual Port RAM

Symbol	Parameter	Value			Unit
		Min.	Type	Max.	
t$_{ASU}$	Setup time A10-0, BHEN, MCSN0-1, WRN (only Motorola mode) to falling edge of WRN (Intel mode) or RDN (Motorola mode with low active strobe) or rising edge RDN (Motorola mode with high active strobe)	0			ns
t$_{AHD}$	Hold time A10-0, BHEN, MCSN0-1, WRN (only Motorola mode) to rising edge of WRN (Intel mode) or RDN (Motorola mode with low active strobe) or rising edge RDN (Motorola mode with high active strobe)	0			ns
t$_{MWRW}$	Pulse width WRN or RDN	30			ns
t$_{DSU}$	Setup time D15-0 to end of write access	10			ns
t$_{DHD}$	Hold time D15-0 after end of write access	10			ns
t$_{MBSY}$	Delay WRN or RDN (begin of write access) to BUSYN low			35	ns
t$_{MBHWH}$	Setup time BUSYN high to end of write access	30			ns
t$_{WR1}$	WRN and RDN high after end of write access	40			ns

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4 CONTROL REGISTERS AND RAM DATA STRUCTURES

4.1 CONTROL REGISTER ADDRESSES

The following table is an overview of the control registers. The address is the word address which is input by A6-1. To calculate the byte address, the value has to be multiplied by two. The **reset values** of the control registers are shown in **bold**.

All control registers can be written to and read (R/W), with the exception of the control bits that initiate an action (W). The status registers can only be read (R). When control registers which contain bits that are not used or can only be read, are written to, these bits can be set to 0 or 1; they are not evaluated internally. If control registers are read with bits that are not used, these bits are set to 0.

A6-1	Bit	Name	R/W	Value	Function
0H	0-15	VERSION	R	2	Circuit code (0002H)
1H	0	RSTFL	R/W	0 **1**	Reset has not taken place **Reset has taken place**
	1	SWRST	W	0 1	Do not reset Reset by software
	2				(Not used)
	3	REPON	R/W	0 **1**	Repeater turned off **Repeater turned on**
	4	SREGEN	R		Level at SREGEN pin
	5	REGMODE	R/W	0 **1**	Sampling at the middle of bit **Sampling according to SERCOS interface specification**
	6		R/W	**0** 1	**Baud rate = f_{SCLK} / 16** Baud rate = f_{SCLK} / 32
	7	POLRXD	R/W	**0** 1	**"Light on" when RxD = 0** "Light on" when RxD = 1
	8	PRESYNC	R/W	**0** 1	**No pre-frame sync word** Pre-frame sync word
	9	POLTXD	R/W	**0** 1	**"Light on" when TxD = 0** "Light on" when TxD = 1
	10	ENTSBAUD	R/W	**0** 1	**Baud rate selected by SWSBAUD pin** Baud rate selected by SWSBAUD control bit
	11	SBAUD	R		Level at pin SBAUD
	12	RXDNRZ	R/W	**0** 1	**Receive data is NRZI-coded** Receive data is NRZI-coded
	13	WRSYNC	R/W		**Direct RAM write access** RAM write access internally synchronized
	14	DMAMODE	R/W	**0** 1	**DMAREQR/DMAREQT are static signals** DMAREQR/DMAREQT are pulses
	15				(Not used)

CONTROL REGISTER ADDRESSES (Continued)

A6-1	Bit	Name	R/W	Value	Function
2H	0-5	ENTXD1-6	R/W	0 **1**	Pin TxDn has a high impedance **Pin TxDn is outputting transmit data**
	6	TXDMODE	R/W	0 1	TXDMODE TxD2-6 is outputting ENTXD2-6
	7-9	TMODE0-2	R/W	**0-3** 4,6 5 7	**Test functions are controlled via TM0-1 pins** Continuous signal light Zero bit stream Normal operation
	10-11	TM0-1	R	0	Level at TM0-1
	12	RDIST	R	0 1	Receive data normal Receive data over distortion limit
	13	FIBBR	R	0 1	Filler signal or data is received No edges on receive data
	14-15	LMODE0-1	R/W	**0** 1 2 3	**L_ERRN active by FIBBR and RDIST** L_ERRN active by RDIST L_ERRN active by FIBBR L_ERRN is inactive
3H	0	INTFL0	R	0 1	Interrupt INT0 not active Interrupt INT0 active
	1	ENINT0	R/W	**0** 1	**Interrupt INT0 disabled** Interrupt INT0 disabled
	2	POLINT0	R/W	**0** 1	**Interrupt INT0 1-active** Interrupt INT0 0-active
	3	INTFL1	R	0 1	Interrupt INT1 not active Interrupt INT1 active
	4	ENINT1	R/W	**0** 1	**Interrupt INT1 disabled** Interrupt INT1 enabled
	5	POLINT1	R/W	**0** 1	**Interrupt INT1 1-active** Interrupt INT1 0-active
	6	COMACT	R	**0** 1	**No transmission block is processed** Transmission block is processed
	7	COMBLK	R	0 1	Transmission block 0 is processed Transmission block 1 is processed
	8	ENTMT	R/W	**0** 1	**Do not send data telegrams** Send data telegrams
	9	FLTMT	R	**0** 1	**Data telegram is not sen**t Data telegram is sent
	10	FLRWAIT	R	**0** 1	**Data telegram is not expected** Data telegram is expected
	11	FLREC	R	**0** 1	**Data telegram is not received** Data telegram is received

SGS-THOMSON
MICROELECTRONICS

CONTROL REGISTER ADDRESSES (Continued)

A6-1	Bit	Name	R/W	Value	Function
3H	12	DMAREQT	R	**0** 1	**DMA request of transmit FIFO inactive** DMA request of transmit FIFO active
	13	DMAREQR	R	**0** 1	**DMA request of receive FIFO inactive** DMA request of receive FIFO active
	14	IDLE	R		Level at IDLE pin
	15	RECACTN	R		Level at RECACTN pin
4H		INT_n	R	0 1	Interrupt event has not occurred Interrupt flag active, interrupt event has occurred
		CLR_INT_n	W	0 1	Do not modify interrupt flag Clear interrupt flag
	0	INT_RDIST	R/W		Interrupt receive data distorted
	1	INT_FIBBR	R/W		Interrupt no receive data
	2	INT_COMBLK0	R/W		Interrupt start transmission block 0
	3	INT_COMBLK1	R/W		Interrupt start transmission block 1
	4	INT_COMEND	R/W		Interrupt end of transmission block
	5	INT_PHAS0	R/W		Interrupt phase MST = 0.
	6	INT_PHASERR	R/W		Interrupt phase MST errored
	7	INT_MSTEARLY	R/W		Interrupt communication cycle start too early
	8	INT_MSTLATE	R/W		Interrupt communication cycle start too late
	9	INT_MSTMISS	R/W		Interrupt MST missing twice
	10	INT_TSTART	R/W		Interrupt start of transmit telegram
	11	INT_TEND	R/W		Interrupt end of transmit telegram
	12	INT_RWAIT	R/W		Interrupt start waiting for receive telegram
	13	INT_RSTART	R/W		Interrupt start of receive telegram
	14	INT_REND	R/W		Interrupt end of receive telegram
	15	INT_RERR	R/W		Interrupt error of receive telegram
5H	0-7	INT_SC_0-7	R/W		Interrupt service container
	8	INT_RMISS	R/W		Interrupt receive telegram missing twice
	9-12	INT_TIME0-3	R/W		Interrupt time TINT0-3
	13	INT_DIVCLK	R/W		Interrupt DIVCLK signal
	14	INT_PROGERR	R/W		Interrupt programming error
	15	INT_NEWADR	R/W		Interrupt address change

CONTROL REGISTER ADDRESSES (Continued)

A6-1	Bit	Name	R/W	Value	Function
6H	0-15	EN0_INT_n	R/W	0 1	Interrupt flag does not activate INT0 Interrupt flag activates INT0 Bit assignment same as for address 4H
7H	0-15	EN0_INT_n	R/W	0 1	Interrupt flag does not activate INT0 Interrupt flag activates INT0 Bit assignment same as for address 5H
8H	0-15	EN1_INT_n	R/W	0 1	Interrupt flag does not activate INT1 Interrupt flag activates INT1 Bit assignment same as for address 4H
9H	0-15	EN1_INT_n	R/W	0 1	Interrupt flag does not activate INT1 Interrupt flag activates INT1 Bit assignment same as for address 5H
OAH	0-7	PHAS0	R/W		Phase for MST transmit (master) or MST receive (slave) **(reset value = 0FFH)**
	8-15	PHAS1	R/W		Phase for MST receive (slave) **(reset value = 0FFH)**
OBH	0-7	PHASREC	R		Phase information of received MST
	8-15	RECADR	R		Address of receive telegram
0CH	0	MSTEN	R/W	0 1	MST is not transmitted or received MST is transmitted or received (SERCOS interface mode)
	1	MSTMASTER	R/W	0 1	Receive MST (SERCOS interface slave) Transmit and receive MST (SERCOS interface master)
	2	COMBLK0	R/W	0 1	When phase = PHAS0 transmission block 0 is processed When phase = PHAS0 transmission block 1 is processed
	3	COMBLK1	R/W	0 1	When phase = PHAS1 transmission block 0 is processed When phase = PHAS1 transmission block 1 is processed
	4	CON_CLK	R		Level at CON_CLK pin
	5	ENCONCLK	R/W	0 1	CON_CLK pin doesn't become active CON_CLK pin becomes active from TINT0 to TINT1
	6	POLCONCLK	R/W	0 1	Signal at CON_CLK is 1-active Signal at CON_CLK is 0-active
	7	CYC_CLK	R		Level at CYC_CLK pin
	8	ENCYCCLK	R/W	0 1	CYC_CLK pin does not trigger timing control CYC_CLK pin triggers timing control after TCYCSTART

SGS-THOMSON MICROELECTRONICS

CONTROL REGISTER ADDRESSES (Continued)

A6-1	Bit	Name	R/W	Value	Function
OCH	9	POLCYCCLK	R/W	0 1	Timing control triggered by rising edge of CYC_CLK Timing control triggered by falling edge of CYC_CLK
	10	CYCSTART	W	0 1	No function Trigger timing control after TCYCSTART (master)
	11	RDTCNT	W	0 1	Do not read TCNT Load TCNT to TCNTRD
	12-15	NCYC	R/W		Number of communcation cycles triggered by CYC_CLK or CYCSTART
0DH	0-7	HS_TIMEOUT	R/W		Handshake timeout for service channel
	8-15	BUSY_TIMEOUT	R/W		BUSY timeout for service channel
0EH	0-4	MCLKDIV	R/W		Predivider value: fMCLK/1 MHz - 1 **(reset value = 19)**
	5-7				(Not used)
	8-12	MCLKST	R/W		Initial value for predivider
	13-15				(Not used)
0FH	0-15	TSCYC0	R/W		SERCOS interface cycle time in ◄s for transmission block 0
10H	0-15	TSCYC1	R/W		SERCOS interface cycle time in ◄s für transmission block 1
11H	0-15	TCYCDEL	R		Time at which MST is received, ring delay (master)
12H	0-15	TCNTLT	R		Stored value of TCNT time counter
13H	0-15	TCNTST	R/W		Initial value for TCNT time counter
14H	0-15	TCYCSTART	R/W		Delay in triggering timing control
15H	0-15	JTSCYC1	R/W		Receive time window for MST 1
16H	0-15	JTSCYC2	R/W		Receive time window for MST 2
17H	0-15	PROGERR_FL	R		Error flags
		CLR_PROGERR_FL	W		Clear error flags
18H	0-15	JTRDEL1	R/W		Receive time window for data telegram 1
19H	0-15	JTRDEL2	R/W		Receive time window for data telegram 2
1AH	0-15	TINT0	R/W		Time at which time interrupt 0 and first edge of CON_CLK occur
1BH	0-15	TINT1	R/W		Time at which time interrupt 1 and second edge of CON_CLK occur

SGS-THOMSON MICROELECTRONICS

CONTROL REGISTER ADDRESSES (Continued)

A6-1	Bit	Name	R/W	Value	Function
1CH	0-15	TINT2	R/W		Time at which time interrupt 2 occurs
1DH	0-15	TINT3	R/W		Time at which time interrupt 3 occurs
1EH	0-15	TDIVCLK	R/W		Time at which the first pulse of DIV_CLK occurs
1FH	0-15	DTDIVCLK	R/W		DIV_CLK pulse distance
20H	0-7	NDIVCLK	R/W		Number of DIV_CLK pulses within one communication cycle **(reset value =0)**
	8	POLDIVCLK	R/W	**0** 1	**Pulses from DIV_CLK are 1-active** Pulses from DIV_CLK are 0-active
	9-15				(Not used)
21H	0-9	THTPT	R		Internal RAM address of telegram header of transmitted telegram
	10-15				(Not used)
22H	0-15	THT	R		Control word 0 of telegram header of transmitted telegram
23H	0-9	THWPT	R		Internal RAM address of telegram header of a telegram which is expected
	10-15				(Not used)
24H	0-15	THW	R		Control word 0 of telegram header of telegram which is expected
25H	0-9	THRPT	R		Internal RAM address of telegram header of received telegram
	10	MSTTCHK	R/W	**0** 1	**MST receive time is not checked** MST receive time is checked
	11	PHAS12	R/W	**0** 1	**Normal operation** Operating mode for SERCOS interface phase 1 and 2
	12	FLMDTADR	R/W	**0** 1	**Address of receive telegram different from expected value** Address of receive telegram equal to expected value
	13-15				(Not used)
26H	0-15	THR	R		Control word 0 of telegram header of received telegram
27H	0-15	RFIFO	R		Receive FIFO
	0-15	TFIFO	W		Transmit FIFO

SGS-THOMSON MICROELECTRONICS

4.2 DATA STRUCTURES WITHIN THE RAM

In this RAM the first eleven words have a fixed meaning.

A10-1	Contents
0-1	COMPT0-1: Start of transmission blocks 0-1
2-9	SCPT0-7: Address service containers 0-7
10	NMSTERR: Error counter MST

The rest of the RAM can be divided into data structures as required.

4.2.1 Telegram Headers

A telegram header for receive telegram contains the following five control words:

INDEX	Bit	Name	Function
0	0-7	ADR	Telegram address
	8	DMA	Data storage in the internal RAM (DMA = 0) or DMA transfer (DMA = 1)
	9	DBUF	Data in the RAM: single buffer (DBUF = 0) or double buffer (DBUF = 1)
	10	VAL	For single buffering (DMA = 0, DBUF = 0) or DMA transfer (DMA = 1): telegram data is invalid (VAL = 0) or valid (VAL = 1); for double buffering (DMA = 0, DBUF = 1): data in buffer 0 (VAL = 0) or buffer 1 (VAL = 1) is valid. Modified by controller at beginning and end of receive telegrams.
	11	ACHK	Telegrams are received if the address is valid (ACHK = 1) or independent on the received address (ACHK = 0). The received address is stored at ADR.
	12	TCHK	The time of receiving is checked (TCHK = 1) or not checked (TCHK = 0).
	13	RERR	The last telegram was free of error (RERR = 0) or errored or not received (RERR = 1).
	14	0	Marker bit for telegram header of receive telegram.
	15	0	Marker bit for telegram header.
1	0-15	TRT	Time for the start of telegram in µs after end of MST.
2	0-15	TLEN	Length of telegram in data words (not including address).
3	0-9	PT	Word address within the RAM of the next telegram header or the end marker.
	10-15		(Not used)
4	0-15	NERR	Error counter

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DATA STRUCTURES WITHIN THE RAM (Continued)

A telegram header for transmit telegram comprises four control words:

Index	Bit	Name	Function
0	0-7	ADR	Telegram address
	8	DMA	Data storage in the RAM (DMA = 0) or DMA transfer (DMA = 1).
	9	DBUF	Data in RAM: single buffer (DBUF = 0) or double buffer (DBUF = 1).
	10	VAL	For double buffering (DMA = 0, DBUF = 1): data in buffer 0 (VAL = 0) or buffer 1 (VAL = 1) are valid. Set by processor.
	11-12	EN	Data telegram is not to be transmitted (EN = 0), transmitted once (EN = 1), continuously (EN = 2) or transmitted only if the previously received telegram contains the expected address (EN = 3) (PHAS12 =1 and FLMDTADR = 1). If EN is 1 the circuit sets EN to 0 after the transmit telegram has been started.
	13		(Not used)
	14	1	Marker bit for telegram header of transmit telegram.
	15	0	Marker bit for telegram header.
1	0-15	TRT	Time for the start of telegram in •s after the end of MST.
2	0-15	TLEN	Length of the telegram in data words (not including address).
3	0-9	PT	Word address of the next telegram header or the end marker.
	10-15		(Not used)

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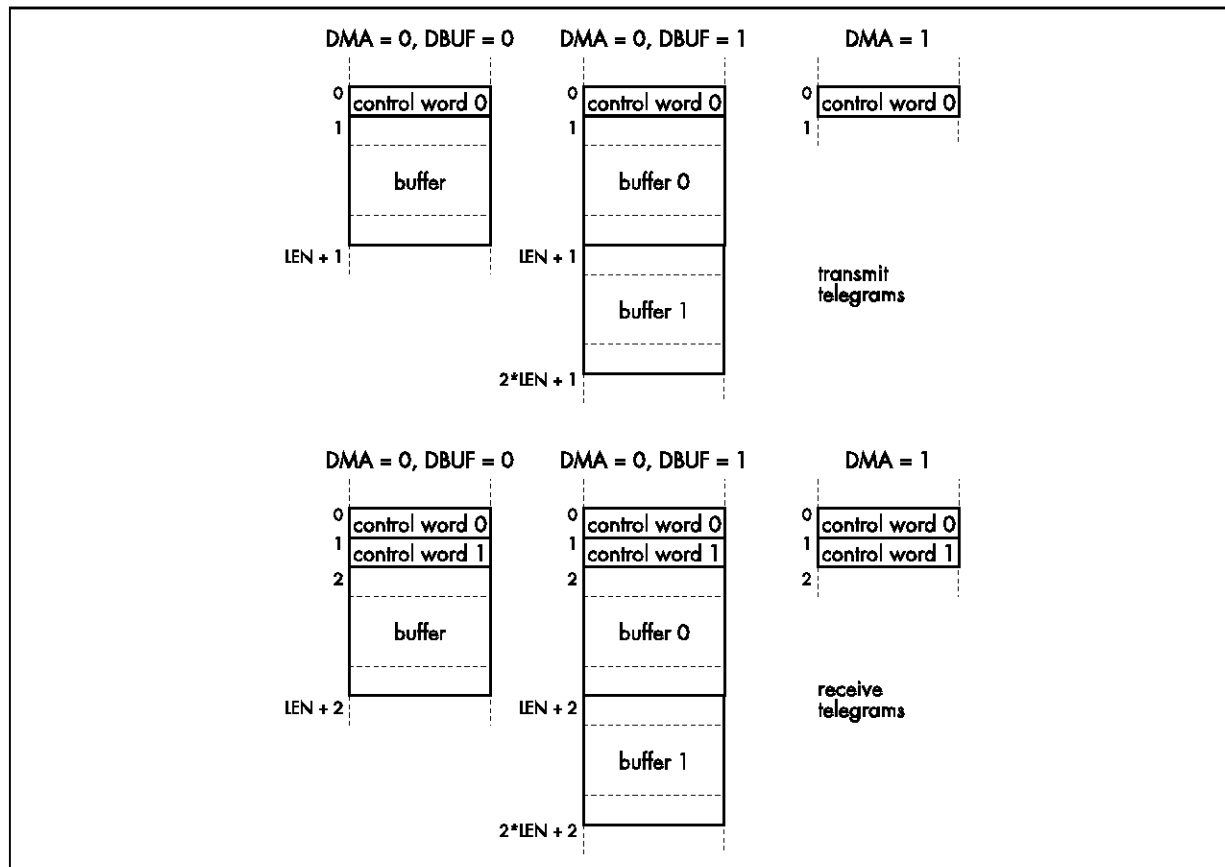## DATA STRUCTURES WITHIN THE RAM (Continued)

4.2.2 Data Containers

A data container comprises one or two 16-bit control words as well as a variable number of data words. If the data is stored in the internal RAM (DMA = 0) and a single buffer is used (DBUF = 0), the data container has one buffer. Using RAM storage and double buffering (DBUF = 1), two data buffers are needed. In case of DMA transfer (DMA = 1) the data container only comprises the control words (Fig. 13). The structure of the two control words depends on whether a telegram is transmitted or received:

Index	Bit	Name	Function
0	0-9	LEN	Number of 16-bit data words of the data block.
	10	SVFL	Flag, whether data block uses service container (SVFL = 1).
	11-13	NSV	Number of service container, which is used (0 - 7).
	14	SCMASTER	Processing of service container in slave mode (SCMASTER = 0) or master mode (SCMASTER = 1).
	15	LASTDC	Last data container of the telegram (1) or further data containers follow (0).
1	0-15	POS	Position of the data block within the telegram in number of words. The first data record of a telegram has POS = 0 (only in case of receive telegrams).

Figure 13. Structure of Data Containers

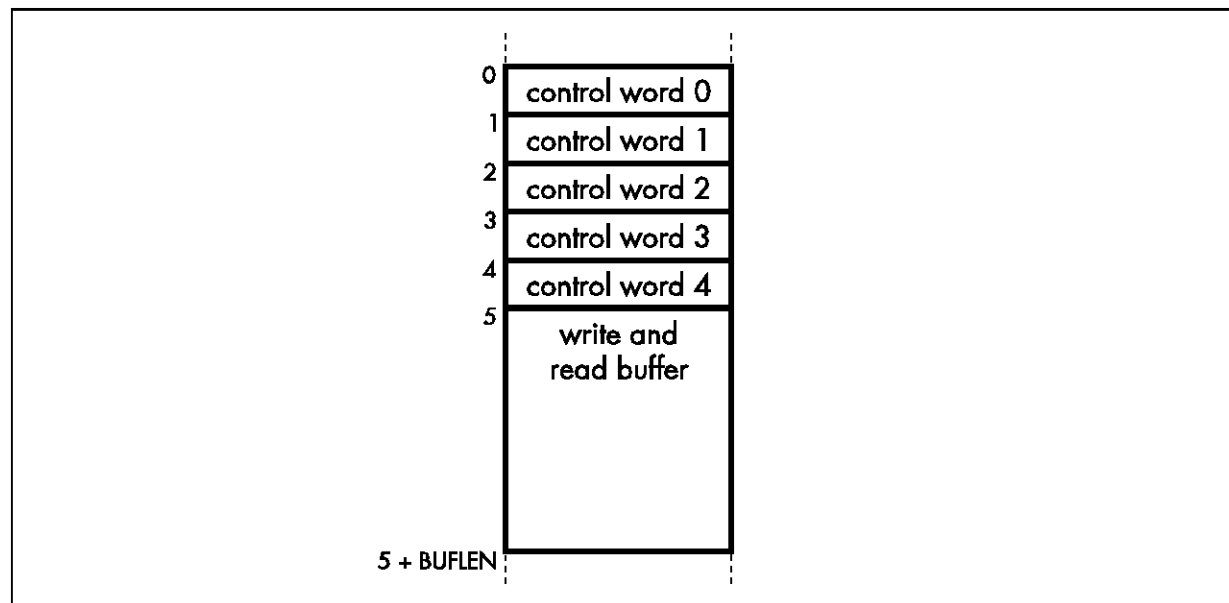## DATA STRUCTURES WITHIN THE RAM (Continued)

4.2.3 End Marker

The end marker comprises two 16-bit words:

Index	Bit	Name	Function
0	0-13		(Not used)
	14	1	Marker bit for the end marker.
	15	1	Marker bit for the end marker.
1	0-15	TEND	Time after end of MST at which the last telegram has ended (in μs).

4.2.4 Service Containers

A service container contains 5 control words and a buffer (BUFLEN words, max. length 255) (Fig. 14)

Figure 14. Structure of Service Container

DATA STRUCTURES WITHIN THE RAM (Continued)

For master mode (SCMASTER = 1) the control words are coded as follows:

Index	Bit	Name	Function
0	0	HS_MDT	Handshake-bit in MDT
	1	L/S_MDT	Read/write in MDT
	2	END_MDT	End in MDT
	3-5	ELEM_MDT	Data element type in MDT
	6	SETEND	END_MDT is to be set
	7	M_BUSY	Service container waits for interaction of microprocessor (M_BUSY = 1)
	8-9	NINFO_WRITE	Number of info words in write buffer (1 to 4)
	10-11		(Not used)
	12	INT_ERR	Slave reports error
	13	INT_END_WRBUF	End of write buffer is reached
	14	INT_END_RDBUF	End of read buffer is reached
	15		(Not used)
1	0	HS_AT	Handshake bit in AT
	1	BUSY_AT	Busy bit in AT
	2	ERR_AT	Error bit in AT
	3	CMD_AT	Command modification bit in AT
	4-6		(Not used)
	7	RECERR	Last transmission was correct (0) or erroneous (1)
	8-9	NINFO_READ	Number of info words in read buffer (1 to 4)
	10-15		(Not used)
2	0-7	WRDATPT	Pointer to present position in write buffer
	8-15	WRDATLAST	Pointer to last position in write buffer
3	0-7	RDDATPT	Pointer to present position in read buffer
	8-15	RDDATLAST	Pointer to last position in read buffer
4	0-7	ERR_CNT	Error counter
	8	BUSY_CNT	Error counts differences of handshake (0) or BUSY cycles (1)
	9	INT_SC_ERR	Interrupt due to protocol error
	10	INT_HS_TIMEOUT	Interrupt due to handshake timeout
	11	INT_BUSY_TIMEOUT	Interrupt BUSY timeout
	12	INT_CMD	Slave has set command modification bit
	13-15		(Not used)

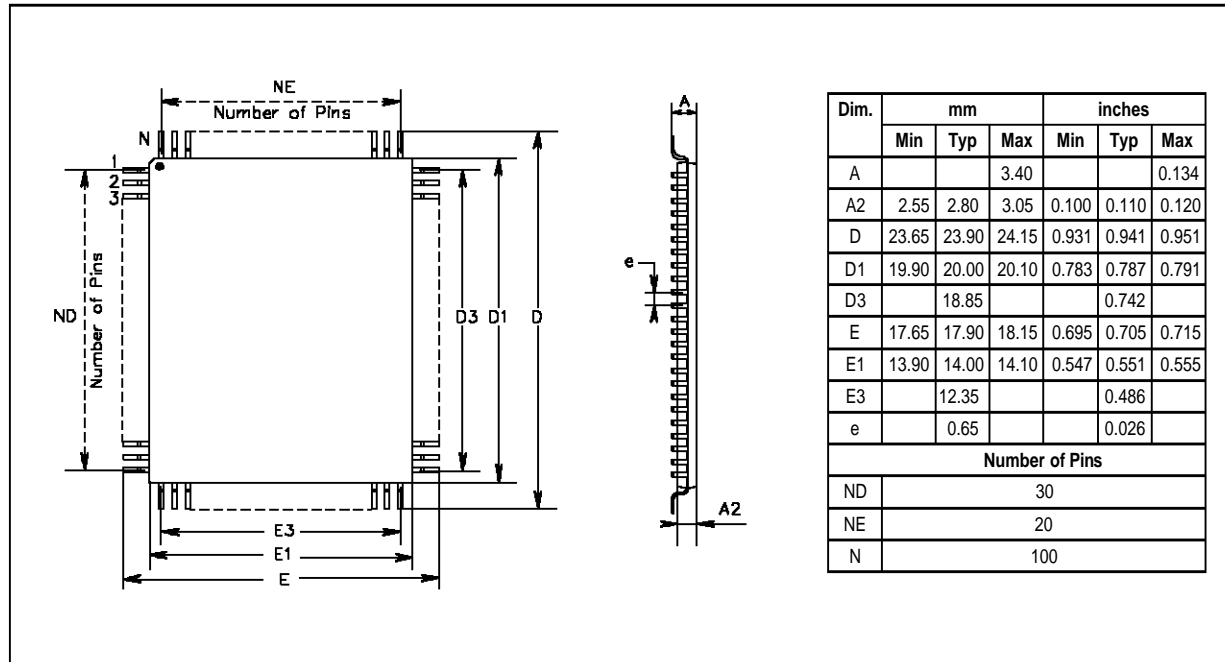## DATA STRUCTURES WITHIN THE RAM (Continued)

The coding of the five control words depends on the mode of the service channel. Using the slave mode (SCMASTER = 0) they have the following structure:

Index	Bit	Name	Function
0	0	HS_AT	Handshake bit in AT
	1	BUSY_AT	Busy bit in AT, also waiting for microprocessor interaction
	2	ERR_AT	Error bit in AT
	3	Error bit in AT	Command modification bit in AT
	4-6	ELEM	Data element of present transmission
	7	L/S	Read (0)/write (1) of present transmission
	8-9	NINFO_WRITE	Number of info words in write buffer (1 to 4)
	10-11		(Not used)
	12	INT_ELEM_CHANGE	Master has modified data element or read/write
	13	INT_END_WRBUF	End of write buffer is reached
	14	INT_END_RDBUF	End of read buffer is reached
	15	INT_END_MDT	Master reports end via END_MDT-bit
1	0	HS_MDT	Handshake bit in MDT
	1	L/S_MDT	Read/write in MDT
	2	END_MDT	End bit in MDT
	3-5	ELEM_MDT	Data element in MDT
	6		(Not used)
	7	RECERR	Last transmission was correct (0) or errorneous (1)
	8-9	NINFO_READ	Number of info words in read buffer (1 to 4)
	10-15		(Not used)
2	0-7	WRDATPT	Pointer to present position in write buffer
	8-15	WRDATLAST	Pointer to last position in write buffer
3	0-7	RDDATPT	Pointer to present position in read buffer
	8-15	RDDATLAST	Pointer to last position in read buffer
4	0-8		(Not used)
	9	INT_SC_ERR	Interrupt due to protocol error
	10-15		(Not used)

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5 PACKAGE MECHANICAL DATA

Figure 15. SERCON410B 100 Pin Plastic Quad Flat Pack Package

Dim.	mm			inches		
	Min	Typ	Max	Min	Typ	Max
A			3.40			0.134
A2	2.55	2.80	3.05	0.100	0.110	0.120
D	23.65	23.90	24.15	0.931	0.941	0.951
D1	19.90	20.00	20.10	0.783	0.787	0.791
D3		18.85			0.742	
E	17.65	17.90	18.15	0.695	0.705	0.715
E1	13.90	14.00	14.10	0.547	0.551	0.555
E3		12.35			0.486	
e		0.65			0.026	
Number of Pins						
ND	30					
NE	20					
N	100					

6 ADDITIONAL SUPPORT AND TOOLS

6.1 SERCOS INTERFACE SPECIFICATION

The SERCOS interface specification is available at:

Fördergemeinschaft SERCOS interface e.V.

Herseler Str. 31

D-50389 Wesseling

Tel. xx49-2236-1517

Fax. xx49-2236-1542

6.2 SOFTWARE AND BOARDS FOR THE SERCON410B

Driver software SERCDRV

Master and slave routines for the SERCON410B

Written in ANSI-C

Independent from operating system and processor

Contains:

- initialization
- start-up of SERCOS interface (phases 0 - 4)
- service channel transmission

Easy portable to many microprocessors and hardware platforms

PC-AT board SERCEB

16-bit ISA bus

Receiver and transmitter for fibre optics (SERCOS interface standard)

SERCON410B and additional timerchip 82C54

Additional RS-485-signals for serial connection and synchronization

Wire wrap area for extension

Add-on board SERCINT

Multiplexed 16-bit address/data-bus

Receiver and transmitter for fibre optics (SERCOS interface standard)

SERCON410B

Additional RS-485-signals for serial connection

These software and boards are available at:

IAM GmbH

Vertrieb Systemtechnik

Richard-Wagner-Str. 1

D-38106 Braunschweig

Tel. xx49-531-3802-0

Fax. xx49-531-3802-110

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NOTES:

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